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(54) **Title:** ULTRA LOW LOSS DIELECTRIC THERMOSETTING RESIN COMPOSITIONS AND HIGH PREFORMANCE LAMINATES MANUFACTURED THEREFROM

(57) **Abstract:** A ultra low loss dielectric thermosetting resin composition has at least one cyanate ester component (A) and at least one reactive intermediate component (B) that is capable of copolymerization with said component (A). The composition exhibits excellent dielectric properties and yields a high performance laminate for use in high layer count, multilayer printed circuit board (PCB), prepregs, resin coated copper (RCC), film adhesives, high frequency radomes, radio frequency (RF) laminates and various composites.



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